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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : RAAIJMAKERS et al.) Group Art Unit: 2825
Appl. No. : 09/452,844)
Filed : December 3, 1999) I hereby certify that this correspondence and all
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Examiner : Rocchegiani, R.)
Adeel S. Akhtar, Reg. No. 41,394

AMENDMENT AND RESPONSE TO ADVISORY ACTION

United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

This paper is responsive to the Advisory Action mailed on January 24, 2002 and is submitted concurrently with a Request for Continued Examination under 37 C.F.R. §1.114. Applicants respectfully request that the application be amended as follows and that the Examiner consider the subsequent arguments.

In the Specification

Please replace the paragraph beginning on page 21, line 21 with the following replacement paragraph:

Note that the parameters in the tables below are exemplary only. Each process phase is desirably arranged to saturate the bottom electrode surfaces. Purge steps are arranged to remove reactants between reactive phases from the reaction chamber. The illustrative ALD processes achieve better than about 95% thickness uniformity, and more preferably greater than about 98% thickness uniformity over HSG grains with average grain sizes of about 400 Å. Thickness uniformity, as used herein, is defined as the thickness minimum as a percentage of the thickness maximum. In view of the disclosure herein, the skilled artisan can readily modify, substitute or